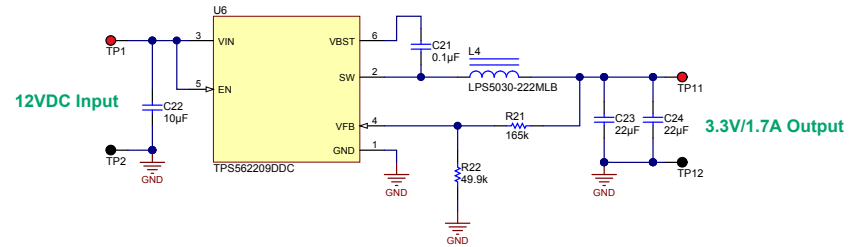


Assembly Notes:
1) Built on PMP9661 Rev A PCB.



PCB
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Designed for:		Mod. Date: 5/1/2014	
Project Title: 12Vin, 3.3V/1.7A Sync Buck			
Number: PMP9725	Rev: A	Sheet Title:	
SVN Rev: Not in version control		Assembly Variant: 001	Sheet: 1 of 1
Drawn By:		File: PMP9725_REVA_SchDoc	Size: B
Engineer: B King		Contact: http://www.ti.com/support	

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